

ABSTRACT

[030] A method and system for testing an integrated circuit package is disclosed. The integrated circuit package includes a plurality of daisy chain loops that are connected to a pair of package pads, wherein adjacent daisy chain loops are oppositely biased. Aspects of the present invention include forming a first plurality of gangs of electrically coupled daisy chain loops having a first bias and forming a second plurality of gangs of electrically coupled daisy chain loops having a second bias. Each one of the first plurality of gangs is individually coupled to an electrical measurement device, while the second plurality of gangs are electrically coupled in common, and the common gang is coupled to the electrical measurement device. According to the method and system disclosed herein, the electrical measurement device may be used to indicate whether there is any leakage between one or more of the first plurality of gangs and the common gang, thereby eliminating the need to use an ATE tester and device under test (DUT) circuit board to perform reliability tests.